

The present invention provides a method of forming a conductive pattern, comprising the steps of: (1) applying a positive, energy-sensitive paste composition containing a conductive powder to a substrate, followed by drying, to form a positive, energy-sensitive coating, (2) irradiating the coating with active energy rays or heat rays directly or through a mask so as to obtain a desired pattern, and (3) removing the irradiated part of the coating by development to form a conductive pattern coating; and

a method of forming a conductive pattern, wherein the above paste composition is applied to a release film and dried, and using the resulting dry film, a conductive pattern coating is formed in a manner similar to the above.